




Product Change Notification - LIAL-11GXQL417

Date:
03 May 2019

Product Category:
Switchtec

Affected CPNs:


Notification subject:
CCB 3779 Initial Notice: Qualification of STAK as an additional bumping facility and assembly site for selected Microsemi products of the 28nm TSMC wafer technology available in 650L BBGA (27x27x2.79mm) package.

Notification text:

PCN Status:
Initial notification.

PCN Type:
Manufacturing Change

Microchip Parts Affected:
Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:
Qualification of STAK as an additional bumping facility and assembly site for selected Microsemi products of the 28nm TSMC wafer technology available in 650L BBGA (27x27x2.79mm) package.

Pre Change:
Assembled at ATK site and bumping facility at ATT using NAU-27 underfill material.

Post Change:
Assembled at ATK site and bumping facility at ATT using NAU-27 underfill material or assembled and bumping facility at STAK site using UF8830S underfill material.

Pre and Post Change Summary:

	Pre Change	Post Change	
Assembly Site	Amkor Technology Korea (K4), INC. (ATK)	Amkor Technology Korea (K4), INC. (ATK)	Stats Chippac Korea Ltd. (STAK)
Bumping facility	Amkor Technology Taiwan (ATT)	Amkor Technology Taiwan (ATT)	
Bump material	SnAg	SnAg	SnAg
Underfill material	NAU-27	NAU-27	UF8830S

Impacts to Data Sheet:



None

Change Impact:

None

Reason for Change:

To improve on time delivery performance by qualifying STAK as an additional bumping facility and assembly site.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

July 2019

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	May 2019					->	July 2019				
Workweek	18	19	20	21	22		27	28	29	30	31
Initial PCN Issue Date	X										
Qual Report Availability							X				
Final PCN Issue Date							X				

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual Plan.

Revision History:

May 3, 2019: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_LIAL-11GXQL417 QUAL PLAN.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.



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Affected Catalog Part Numbers (CPN)

PM8531B-F3EI
PM8532B-F3EI
PM8533B-F3EI
PM8541B-F3EI
PM8542B-F3EI
PM8543B-F3EI
PM8551B-F3EI
PM8552B-F3EI
PM8553B-F3EI
PM8561B-F3EI
PM8562B-F3EI
PM8563B-F3EI
PM8571B-F3EI
PM8572B-F3EI
PM8573B-F3EI